

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE8108EM	**Issued**	18. August 2021
MA#	MA005432707		
Package	PG-SSOP-24-4	**Weight***	150.64 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.956	1.96	1.96	19624	19624
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8930	
	non noble metal	copper	7440-50-8	54.617	36.26	37.20	362578	372066
wire	noble metal	gold	7440-57-5	0.575	0.38	0.38	3818	3818
encapsulation	organic material	carbon black	1333-86-4	0.174	0.12		1155	
	plastics	epoxy resin	-	8.003	5.31		53132	
	inorganic material	silicondioxide	60676-86-0	78.817	52.33	57.76	523230	577517
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19324	19324
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1555	1555
glue	plastics	epoxy resin	-	0.230	0.15		1524	
	noble metal	silver	7440-22-4	0.689	0.46	0.61	4572	6096
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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